



# 规格书

## SPECIFICATION

CUSTOMER NAME	客户名称:	
CUSTOMER NO.	客户编号:	
SERIES	系 列:	D-SUB连接器
MODEL NO.	型 号:	XB-series
DRAWING NO.	图 形 号:	D-SUB Connectors

**If specification of this product meets your request, please confirm all the items of it and return to us with signature and stamp, it will be basis of our production and record. Thanks your cooperation in advance!**

若此产品规格符合贵司要求，敬请确认此规格书内所有项目  
并签名和盖章后回传给我司，以作我司产品制作之  
依据和存档之用，多谢合作！

### EXAMINE & APPROVAL 审批

APPROVE 接受	NOT APPROVE 不接受
<div>SIGNATURE 签署      STAMP 盖章      DATE 日期</div>	

PREPARED BY.制表人	CHECKED BY.校对	APPROVED BY.审核	APPROVAL BY.批准
研发部	品质部	工程部	总经办
戴海明	黄自清	庞军	吴量
2022. 06. 08	2022. 06. 08	2022. 06. 08	2022. 06. 08

东莞市溪榜电子有限公司

**Dong guan Xi Bang Electronics Co., Ltd**  
地址: 广东省东莞市黄江镇合路工业区  
Address: He Lu Industrial Zone, Huangjiang Town  
, Dongguan City, Guangdong Province  
Tel: (0769)82055138/82056828  
Fax: (0769)83663452

邮箱: [admin@alspr.com](mailto:admin@alspr.com)    [switch@alspr.com](mailto:switch@alspr.com)  
<http://www.alspr.cn/>    <http://www.alspr.com/>

Dong Guan XB ElectronicsCo., Ltd

AccountNumber: 705540238  
BankName: CitibankN.A., HongKongBranch  
Country/Region: Hong Kong  
BankCode: 006  
BankAddress: 3GardenRoad, Central, Hong Kong  
SWIFT/BIC: CITIHKHX (CITIHKHXXXX\*If 11 characters are required)  
**Mail:** HK@ALPSR.CN    XB@ALPSR.CN    XB@ALPSR.COM  
**Quality core! Afterburner for Made in China!**



ENGINEERING

DEPT.

PRODUCT SPECIFICATION

For High Density Solder Dip D-Sub  
Connector of System CD01

SPEC.NO.: SPCD001E

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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on Xi Bang connector test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202

Methods for test of connectors for electronic equipment

MIL - STD - 1344

Test methods for electrical connectors

SS-00254

Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO.: **CD01 Series**

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. SOLDER CUP ACCEPTS CABLE: AWG #20 Max.

REVIEWED : XIE.BING.XIN APPROVED : HE.LONG.FEI VERIFIED : PANG.DONG



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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 5000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Contact retaining force in insulator	Retention speed $25 \pm 3$ mm per minute from housing	More than 4.0 Kg <sub>f</sub>
8.2	Single contact insertion force	Measure force to insertion using $\varnothing 0.78$ mm test pin at speed $25 \pm 3$ mm per minute	240 gram max.
8.3	Single contact withdrawal force	Measure force to withdrawal using $\varnothing 0.74$ mm test pin at speed $25 \pm 3$ mm per minute	15 gram min.
8.4	Durability	Connector shall be subjected to 100 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.
9.2	Vibration	1.5 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Solder ability	<b>Tin-Lead Process:</b> Soldering time: $5 \pm 0.5$ second Soldering pot: $230 \pm 5^{\circ}\text{C}$ <b>Lead-Free Process:</b> Soldering time: $3 \pm 0.5$ second Soldering pot: $245 \pm 5^{\circ}\text{C}$	Minimum: 90% of immersed area

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	ITEM	TEST CONDITION	REQUIREMENT
9.4	Hand Soldering	Use a soldering iron that has a sufficient head capacity and high stability of temperature. The tip of the iron should be shaped so as not to touch the part body directly. Temperature : $380 \pm 10^{\circ}\text{C}$ 3Sec.	No damage
9.5	Heat aging	$105 \pm 2^{\circ}\text{C}$ , 96 hours	No damage
9.6	Humidity	$40 \pm 2^{\circ}\text{C}$ , 90-95% RH , 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.7	Temperature cycling	One cycle consists of : (1) $-55^{+0}_{-3}^{\circ}\text{C}$ , 30 min. (2) Room temp. 10-15 min. (3) $85^{+3}_{-0}^{\circ}\text{C}$ , 30 min. (4) Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.8	Salt spray	Temperature: $35 \pm 3^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: $48 \pm 4$ hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE:  $-40$  to  $+105^{\circ}\text{C}$

11. MATING FORCE AND UNMATING FORCE:

Unit: Kgf

No. of Circuits	Mating Force ( Initial max. )	Unmating Force ( Initial max. )
15	5.1	3.8
26	9.2	6.9
44	12.6	8.6
62	16.4	10.8